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Advances in high precision and high-throughput Laser micromachining

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Outline

- ▶ Scale-Up Problem with Single Pulses
- ▶ Multi-Pulse Strategies
 - ▶ Temporal: Pulse bursts (incl. GHz)
 - ▶ Spatial: Multi – spots
- ▶ Beam forming
- ▶ Conclusions/Outlook

Ablation model Gaussian Beam

- ▶ Energy specific Volume [1]:

$$\frac{dV}{dE} = \frac{1}{2} \cdot \frac{\delta}{\phi_0} \cdot \ln^2 \left(\frac{\phi_0}{\phi_{th}} \right)$$

with:

ϕ_{th} : Threshold fluence

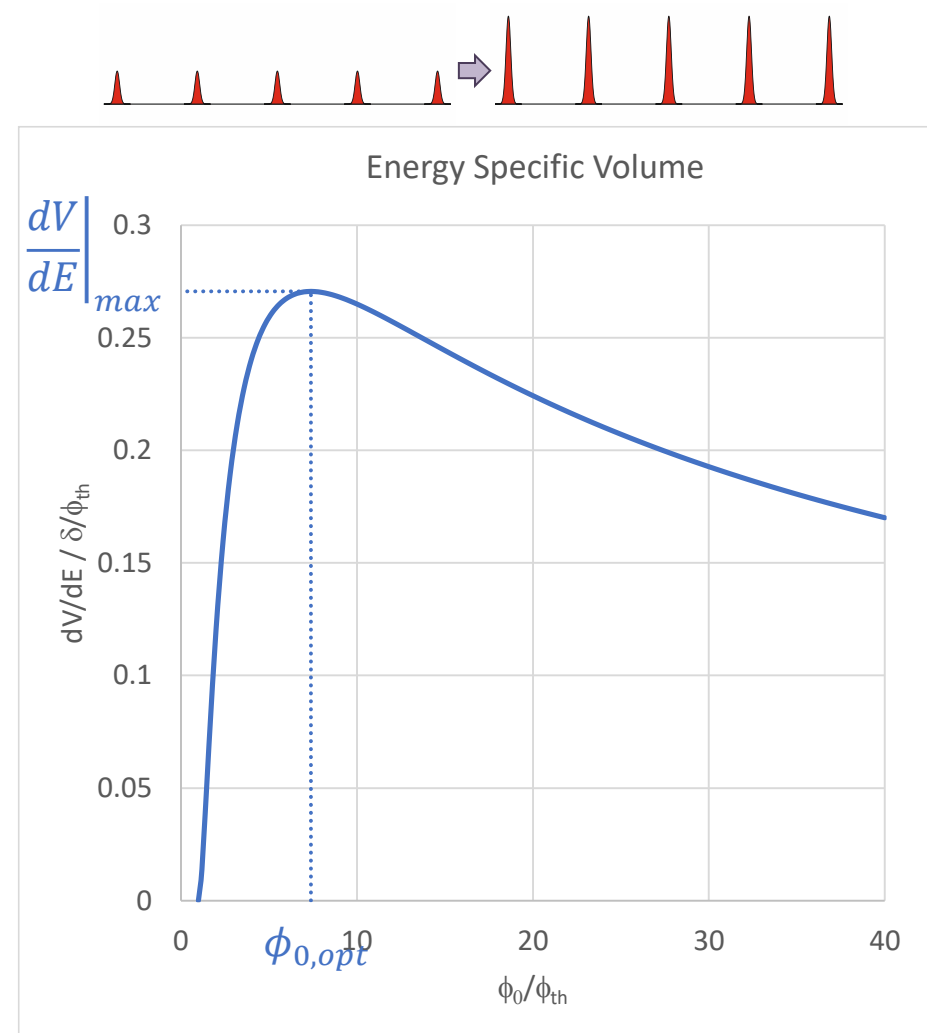
δ : Energy penetration depth

ϕ_0 : Peak fluence

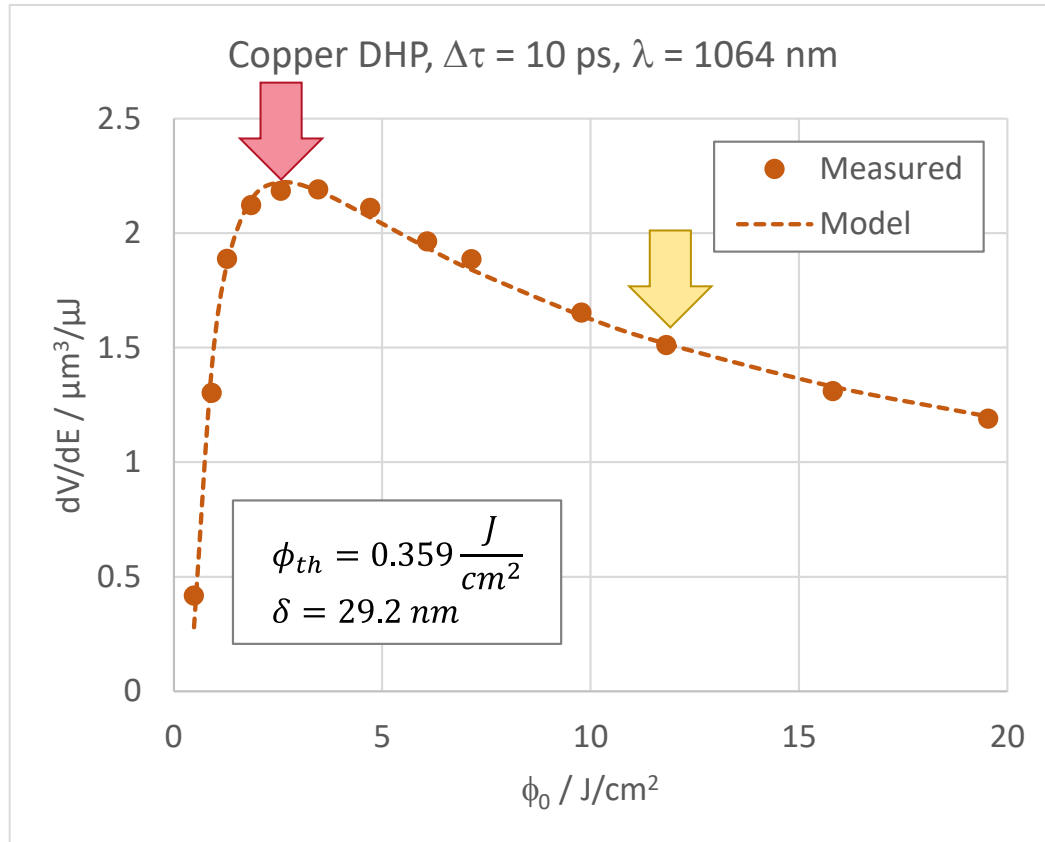
- ▶ Optimum Point / Maximum specific removal rate

$$\phi_{0,opt} = e^2 \cdot \phi_{th} \quad \left. \frac{dV}{dE} \right|_{max} = \frac{2}{e^2} \cdot \frac{\delta}{\phi_{th}}$$

[1]: B. Neuenschwander et al, „From fs to sub-ns: Dependence of the Material Removal Rate on the Pulse Duration for Metals”, Physics Procedia Vol. 41, pp. 787-794 (2013)

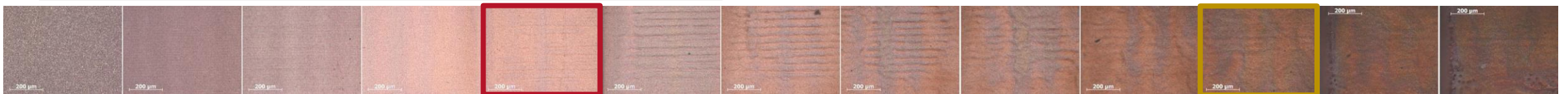


Copper DHP

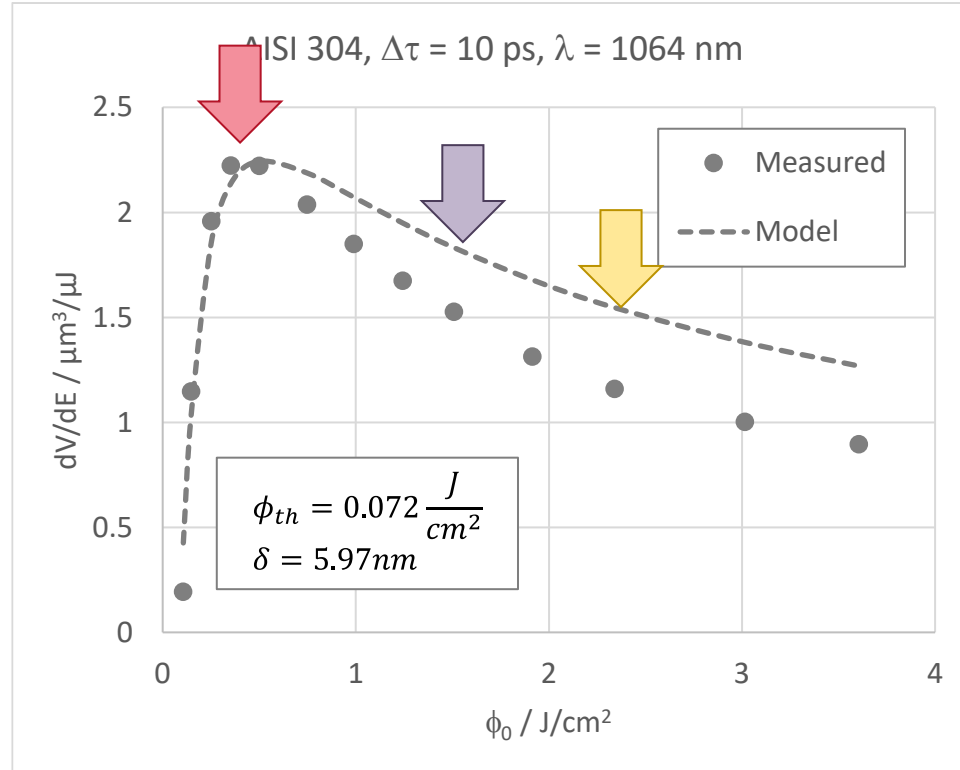


- ▶ High surface quality near optimum point
- ▶ Best strategy: Increase repetition rate
- ▶ But acceptable surface quality for higher peak fluences
- ▶ Scale up by increasing peak fluence i.e. pulse energy is also possible
- ▶ Limited repetition rate, higher fluences corresponds to higher average powers:

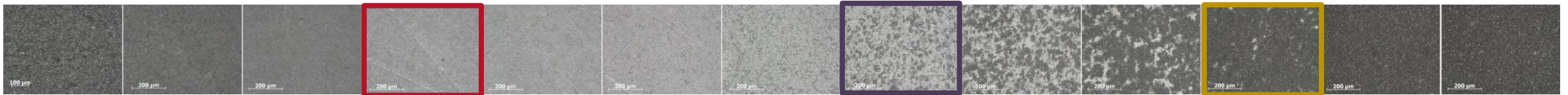
$$\dot{V}_{n \cdot \phi_{opt}} = \frac{(\ln(n) + 2)^2}{4} \cdot \dot{V}_{\phi_{opt}}$$



Steel AISI 304



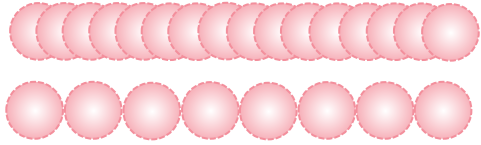
- ▶ High surface quality near optimum point
- ▶ Best strategy: Increase repetition rate
- ▶ Formation of cavities starts for peak fluences of about $E_{pulse} = 2 \cdot E_{opt}$
- ▶ For higher fluences the surface becomes fully covered by cavities (cone like protrusions CLP)
- ▶ Increasing pulse energy fails
- ▶ For several 10 W average power extremely high repetition rates and marking speeds demanded



Scale-Up Strategies

Single Pulse Strategies

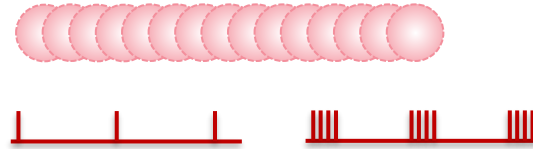
- ▶ Fast scanning



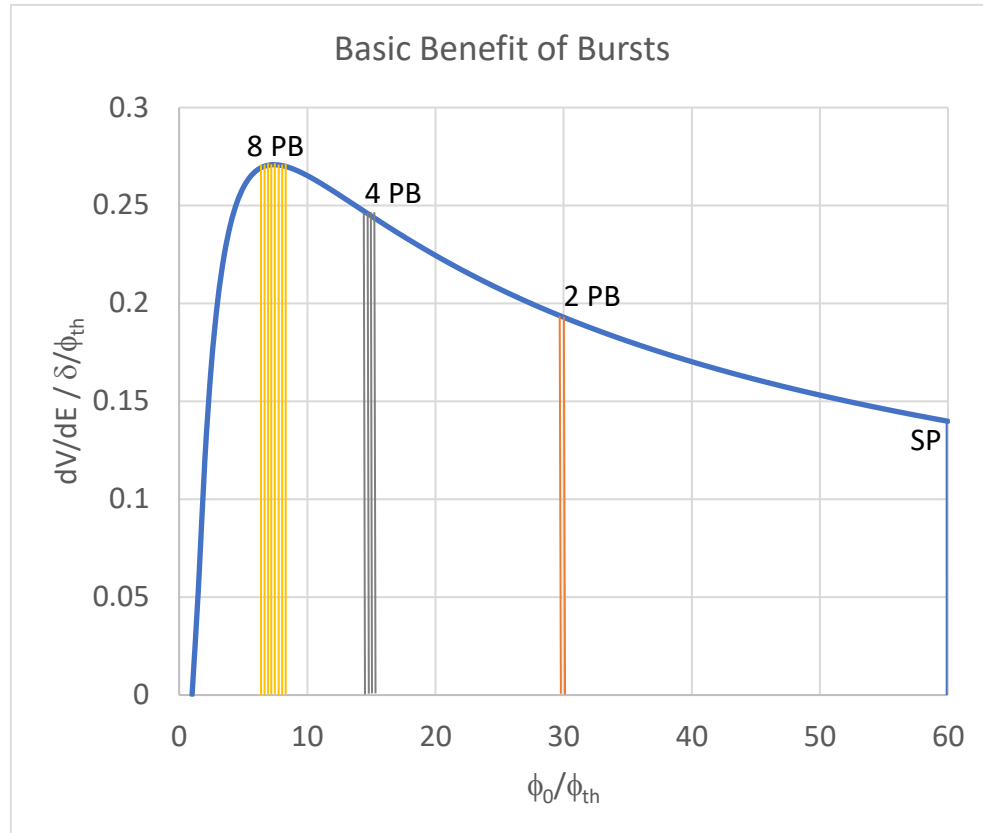
- ▶ Just discussed

Multipulse Strategies

- ▶ Pulse Bursts:



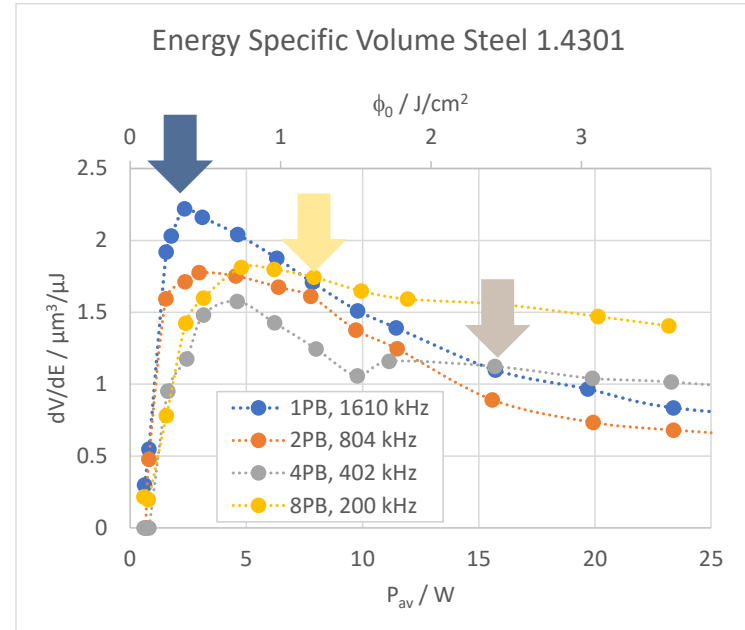
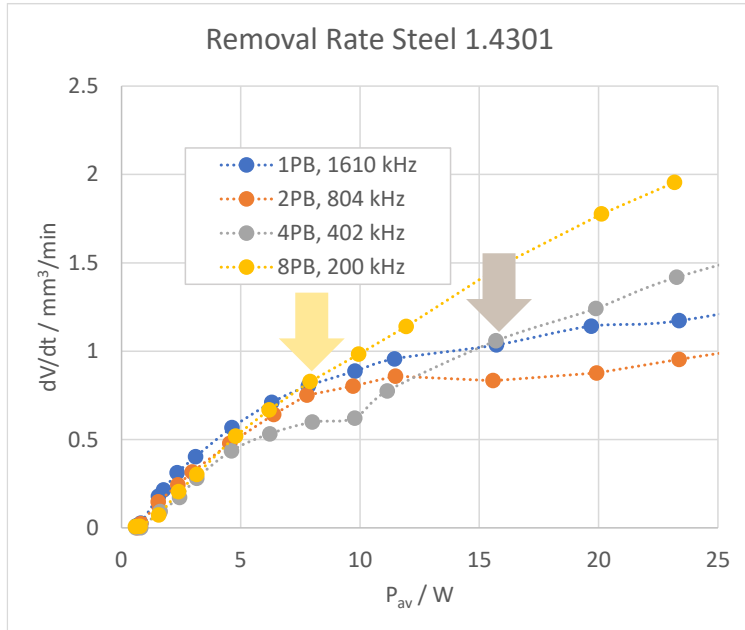
Basic Benefit of Pulse Bursts



[2]: D. Förster et al, „Review on Experimental and Theoretical Investigations of Ultra-Short Pulsed Laser Ablation of Metals with Burst Pulses”, Materials 14(12), 3331 (2021)

- ▶ Total energy of a pulse is distributed among different sub pulses.
- ▶ The fluence of the sub pulses converges to the optimum value
- ▶ The process becomes more efficient
- ▶ Constant average power:
 - ▶ $n_B \cdot f_{rep} = const.$

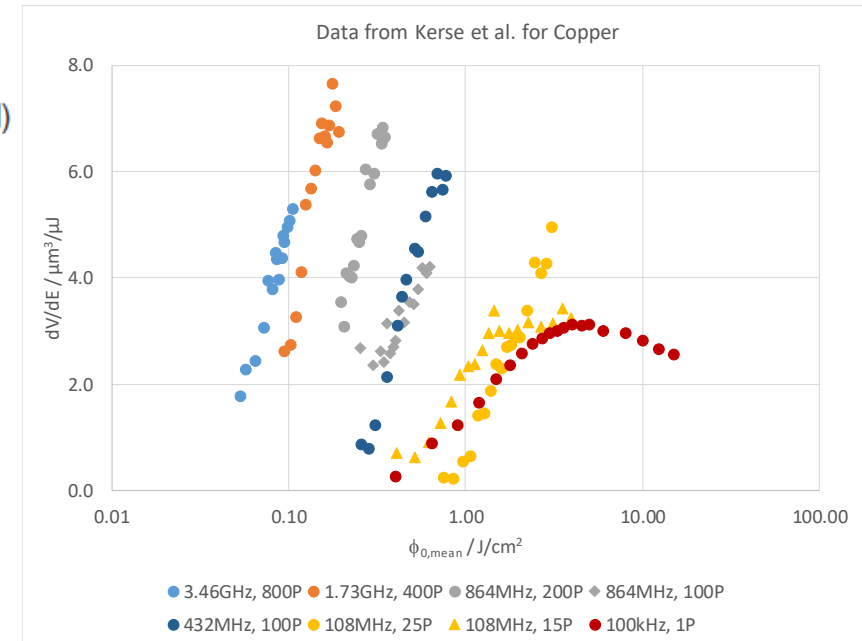
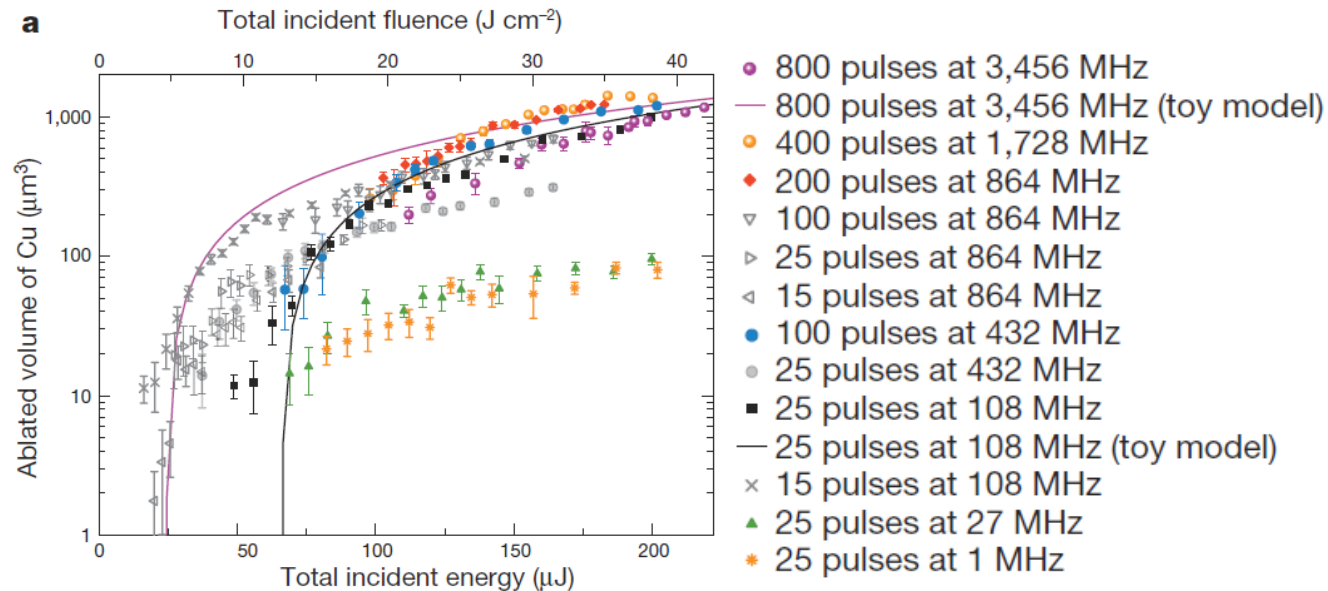
Basic Benefit of Pulse Bursts AISI 304



- ▶ Single pulses are most efficient
- ▶ But for higher average powers a break even can be achieved
- ▶ From there on a burst situation can be more efficient than single pulses

GHz Burst and Ablation Cooling

- ▶ A "Nature" publication states that GHz bursts are highly efficient compared to single pulses due to the enhanced "ablation cooling" effect

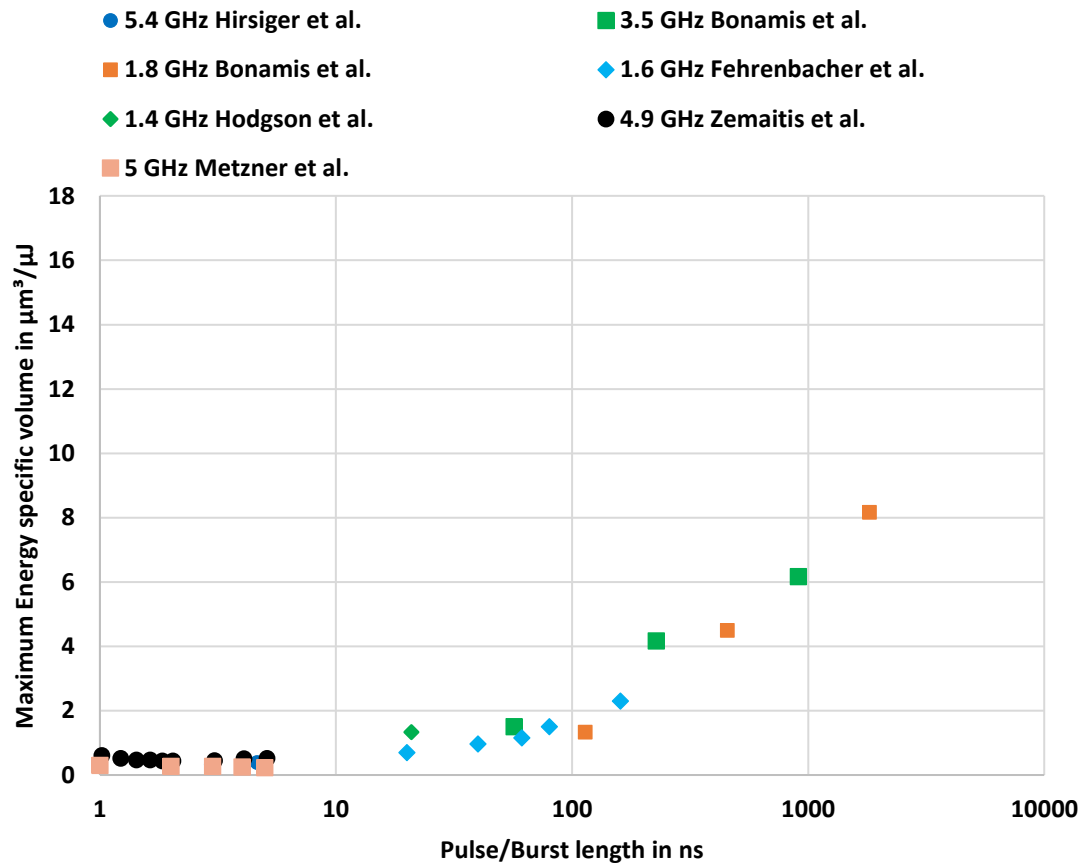


[4]: C. Kerse et al., "Ablation-cooled material removal with ultrafast bursts of pulses" *Nature* 532, 84 – 89 (2016)

- ▶ The obtained specific removal rates are indeed above the ones for single pulses

AISI 304 GHz Bursts

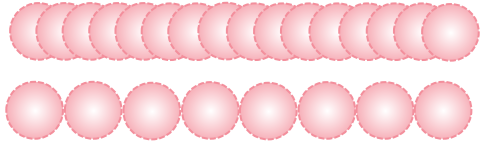
- ▶ For AISI 304 high number of pulses per burst i.e. long burst lengths, lead to higher maximum energy specific volumes



Scale-Up Strategies

Single Pulse Strategies

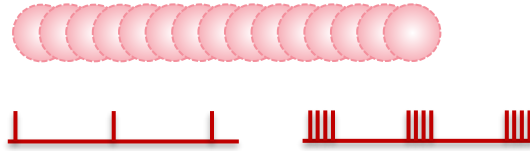
- ▶ Fast scanning



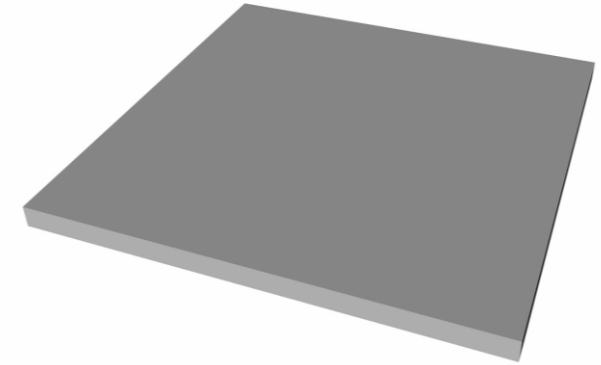
- ▶ limits just discussed

Multipulse Strategies

- ▶ Pulse Bursts:

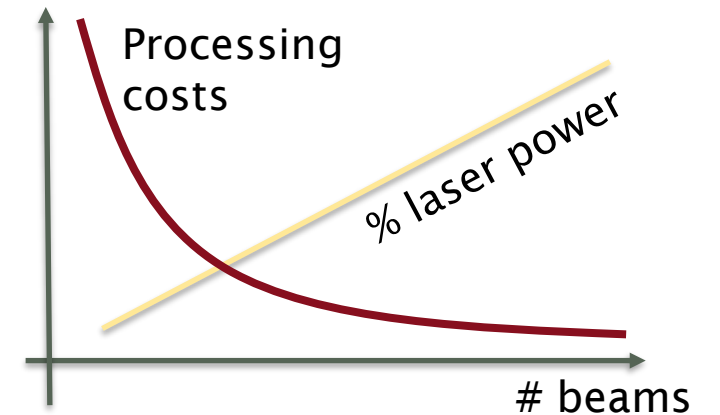


- ▶ Multispots:



<https://www.pulsar-photonics.de>

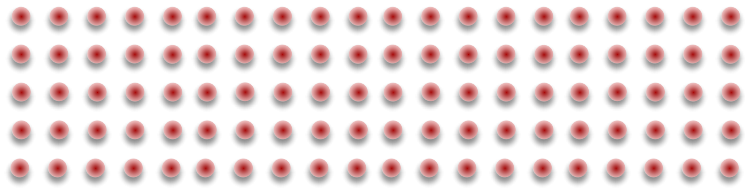
€ / %



- ▶ Limited to periodic structures

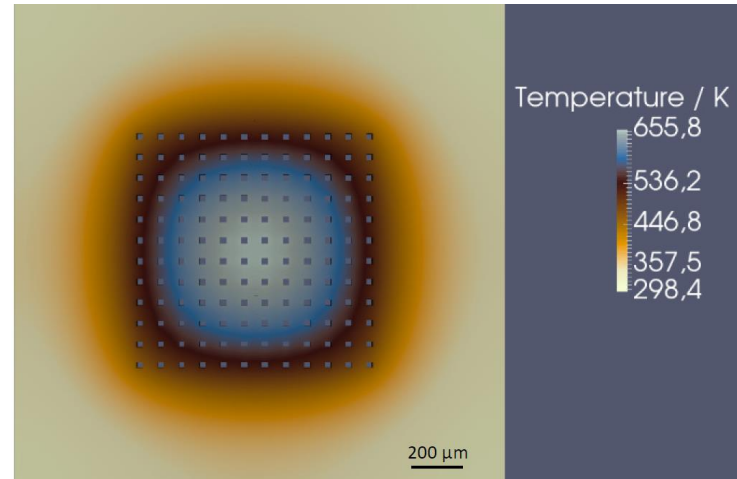
Multi Pulse Drilling

- ▶ Standard percussion drilling with $n \times n$ spots
- ▶ Change position with galvo scanner

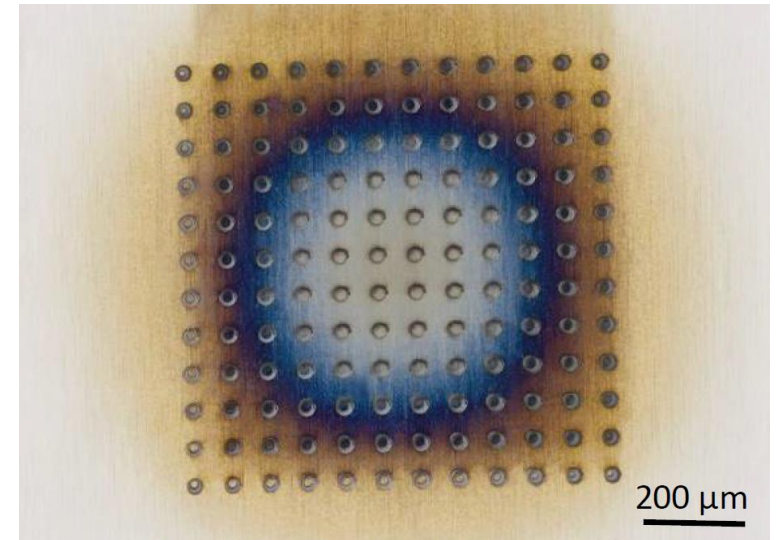


- ▶ The high total energy may lead to heat accumulation problems.

- ▶ Parallel machining with 12×12 Spots [8]
- ▶ Simulation



- ▶ Observed annealing



[8]: D. Gillner et al, „High Power Laser Processing with Ultrafast and Multi-Parallel Beams”, JLMN Journal of Laser Micro/Nanoengineering 14(2), 129-137 (2019)

Optimized Galvo Scanning by Synchronization

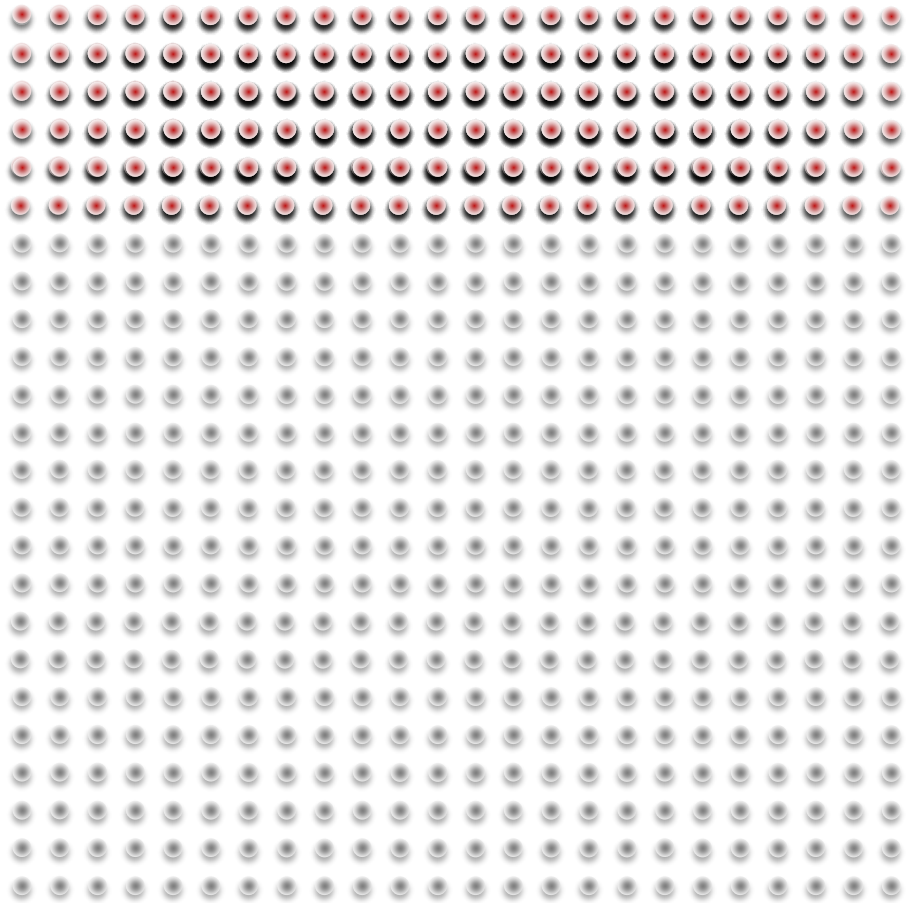
Free Running Scanner Trajectory for Bi-Directional Marking

Synchronized Scanner Trajectory for Bi-Directional Marking

- ▶ Free running
- ▶ Diffuse spot pattern
- ▶ Laser- and line-frequency do not match

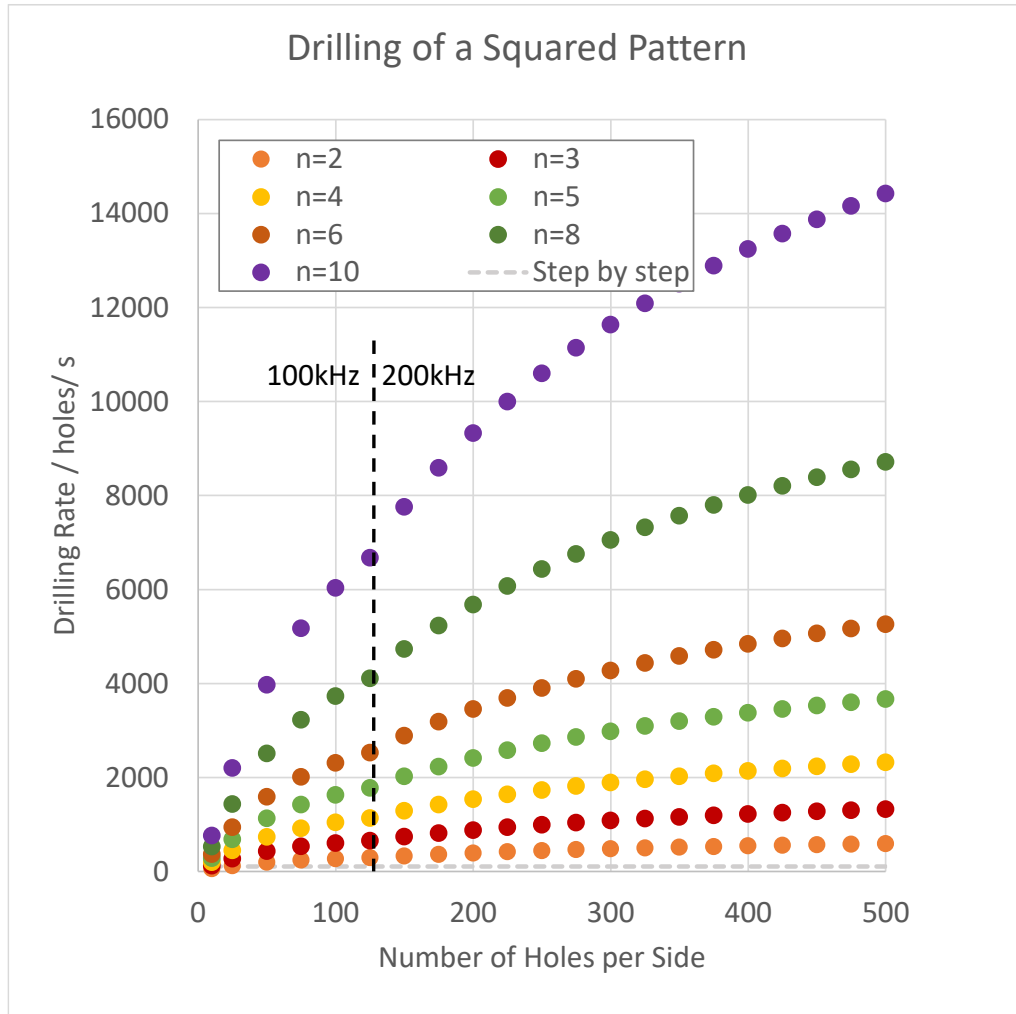
- ▶ Synchronized, laser-frequency is master
- ▶ Regular spot to spot pattern
- ▶ Fully reproducible from layer to layer

Drilling on the Fly by Multi Spot Stamping



- ▶ Stamp multi-spot pattern with $n \times n$ equally spaced spots
- ▶ Move pattern by one spot – spot distance d_x between two pulses

Drilling on the Fly by Multi Spot Stamping



- ▶ Stamp multi-spot pattern with $n \times n$ equally spaced spots
- ▶ Move pattern by one spot – spot distance d_x between two pulses
- ▶ For each point within a frame n^2 pulses are applied
 - ▶ $P_{av,n} = n^2 \cdot P_{av,1}$
 - ▶ $k_n = \text{ceil}\left(\frac{k_1}{n^2}\right)$
- ▶ For a frame with $N \times N$ spots
 - ▶ $(N + n - 2)^2$ points are marked
 - ▶ Mark length: $s_m = (N + n - 2) \cdot d_x$
- ▶ Several 1000 holes/s are achievable with minimum thermal load

Drilling on the Fly by Multi Spot Stamping

Single Spots:

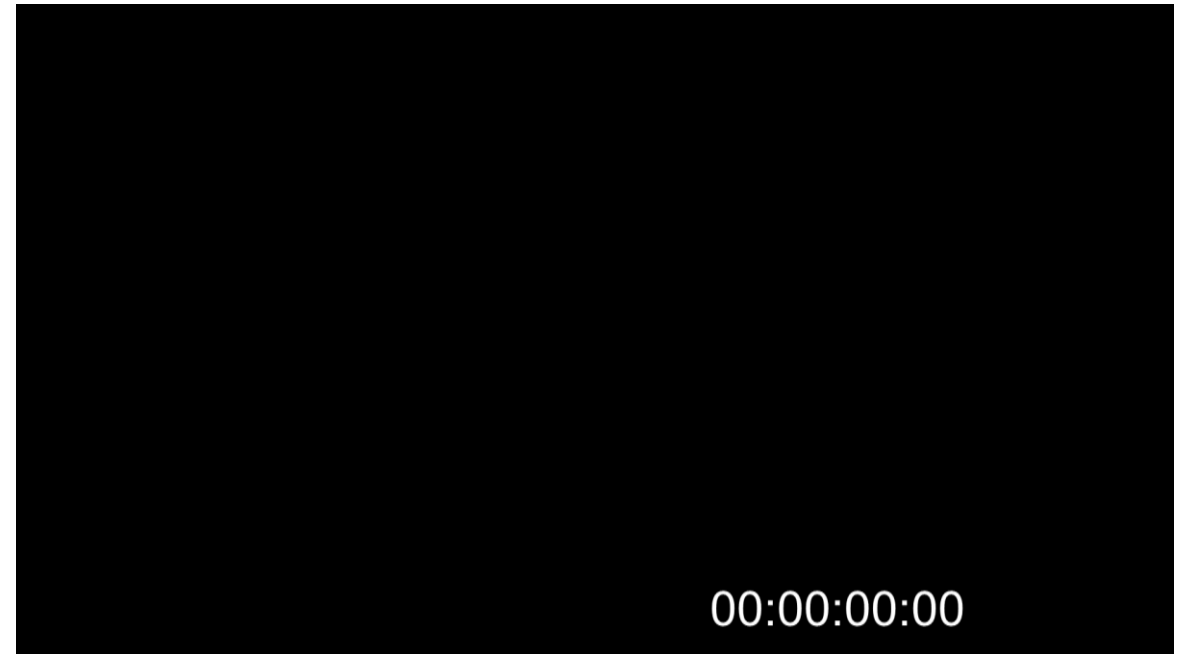
675 Repetitions, $P_{av} = 640 \text{ mW}$



- ▶ $\sim 150s$ for 100×100 holes $\rightarrow \sim 75 \frac{\text{holes}}{s}$
- ▶ for 300×300 holes $\sim 1000s \rightarrow \sim 90 \frac{\text{holes}}{s}$

5x5 Spots with DOE:

27 Repetitions, $P_{av} = 16 \text{ W}$

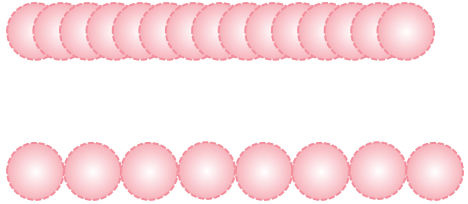


- ▶ $\sim 6s$ for 100×100 holes $\rightarrow \sim 1700 \frac{\text{holes}}{s}$
- ▶ for 300×300 holes $\sim 40s \rightarrow \sim 2250 \frac{\text{holes}}{s}$

Scale-Up Strategies

Single Pulse Strategies

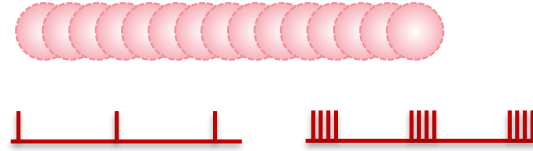
- ▶ Fast scanning



- ▶ limits already discussed

Multipulse Strategies

- ▶ Pulse Bursts:



- ▶ Multispots:



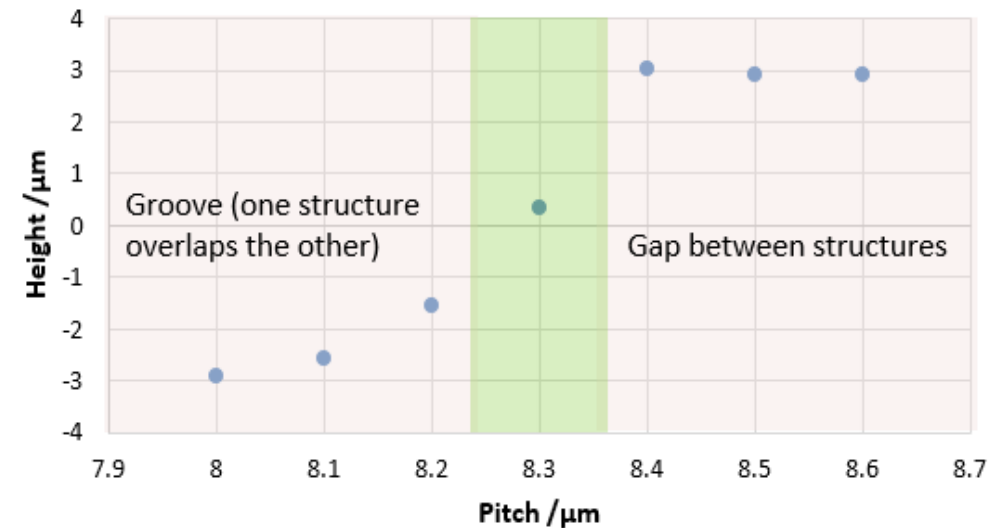
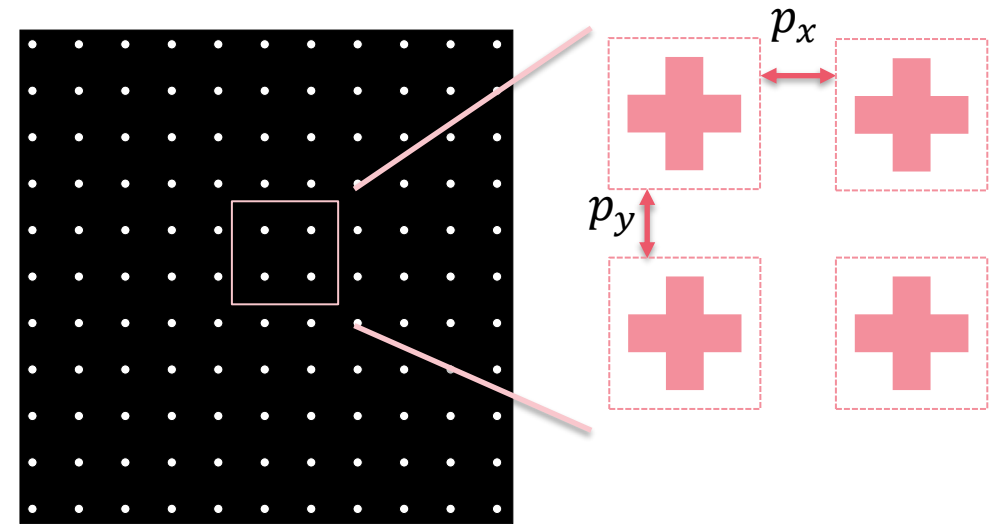
Beam Forming Strategies

- ▶ Directly forming of the desired pattern or parts of it by optical elements (DOE, SLM)



Synchronized Optical Stamping with DOE

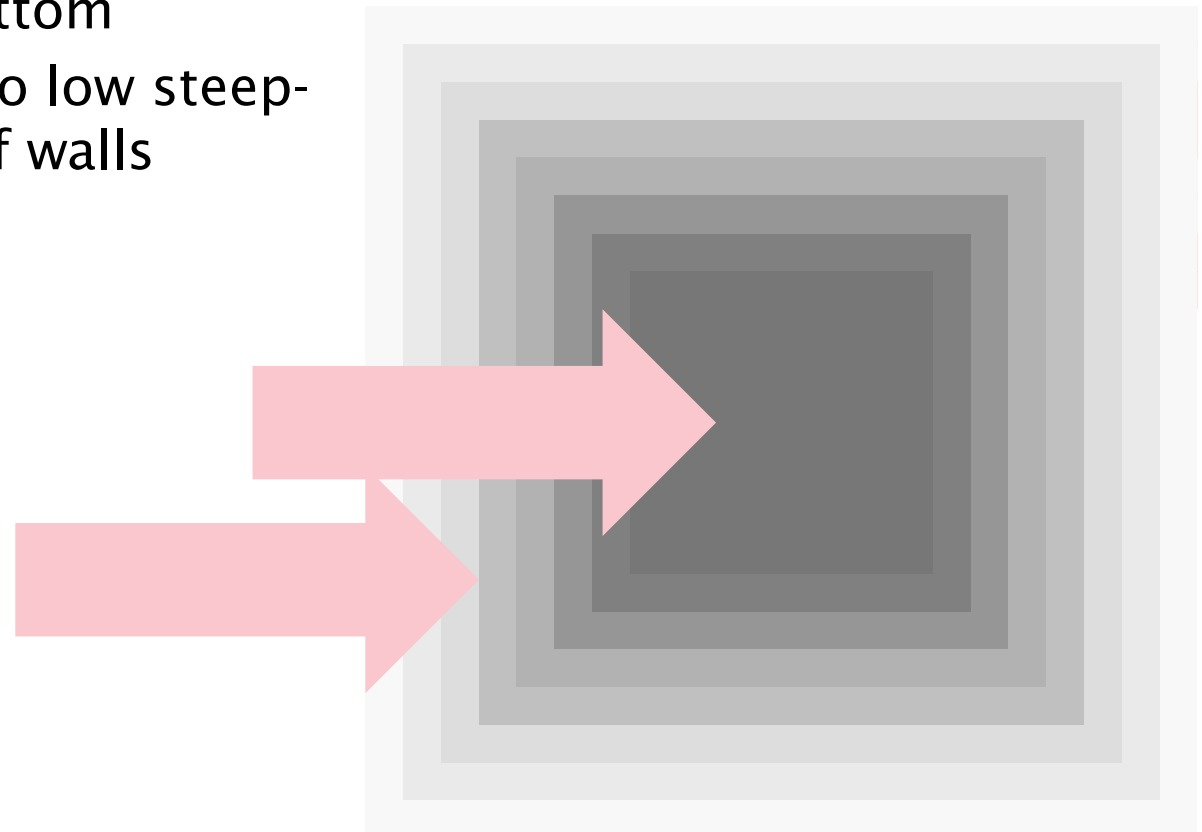
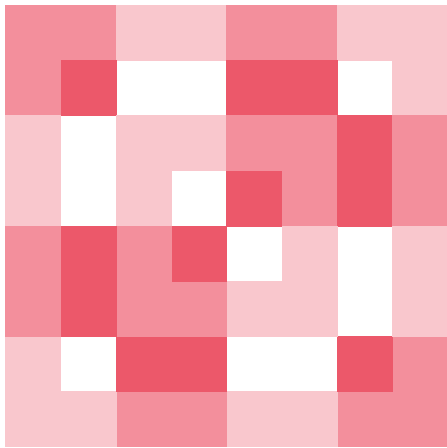
- ▶ DOE to generate an elementary cell and cage system to adjust correct pattern size
- ▶ Good beam quality is important (Gaussian beam) for correct structure
- ▶ Stitching with synchronized galvo scanner
- ▶ Pitch has to be adjusted in both directions



Homogeneous Ablation with 8x8 4 Level Top Hat DOE

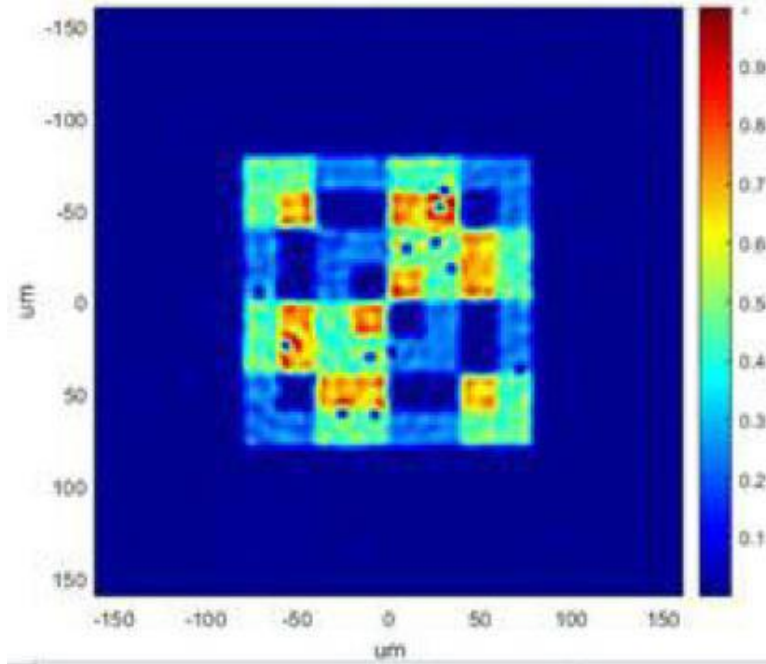
▶ Idea:

- ▶ 8x8 squares of 20 μm side length
- ▶ 4 level top hats 0%, 33%, 66%, 100%
- ▶ Equal sum per line and row (400%)
- ▶ Synchronized scanning
- ▶ Set pulse – pulse and line – line distance to 20 μm
- ▶ Leads to homogeneous flat bottom
- ▶ But also low steepness of walls

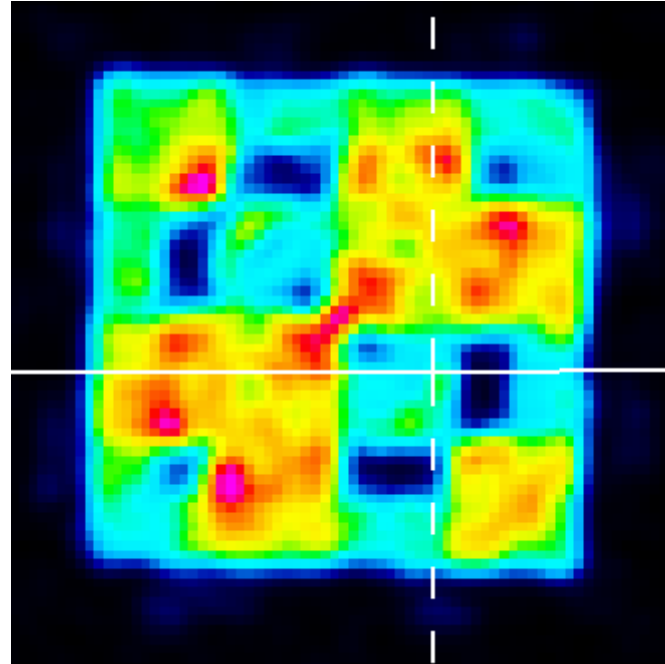


Homogeneous Ablation with 8x8 4 Level Top Hat DOE

▶ Calc. DOE Pattern:

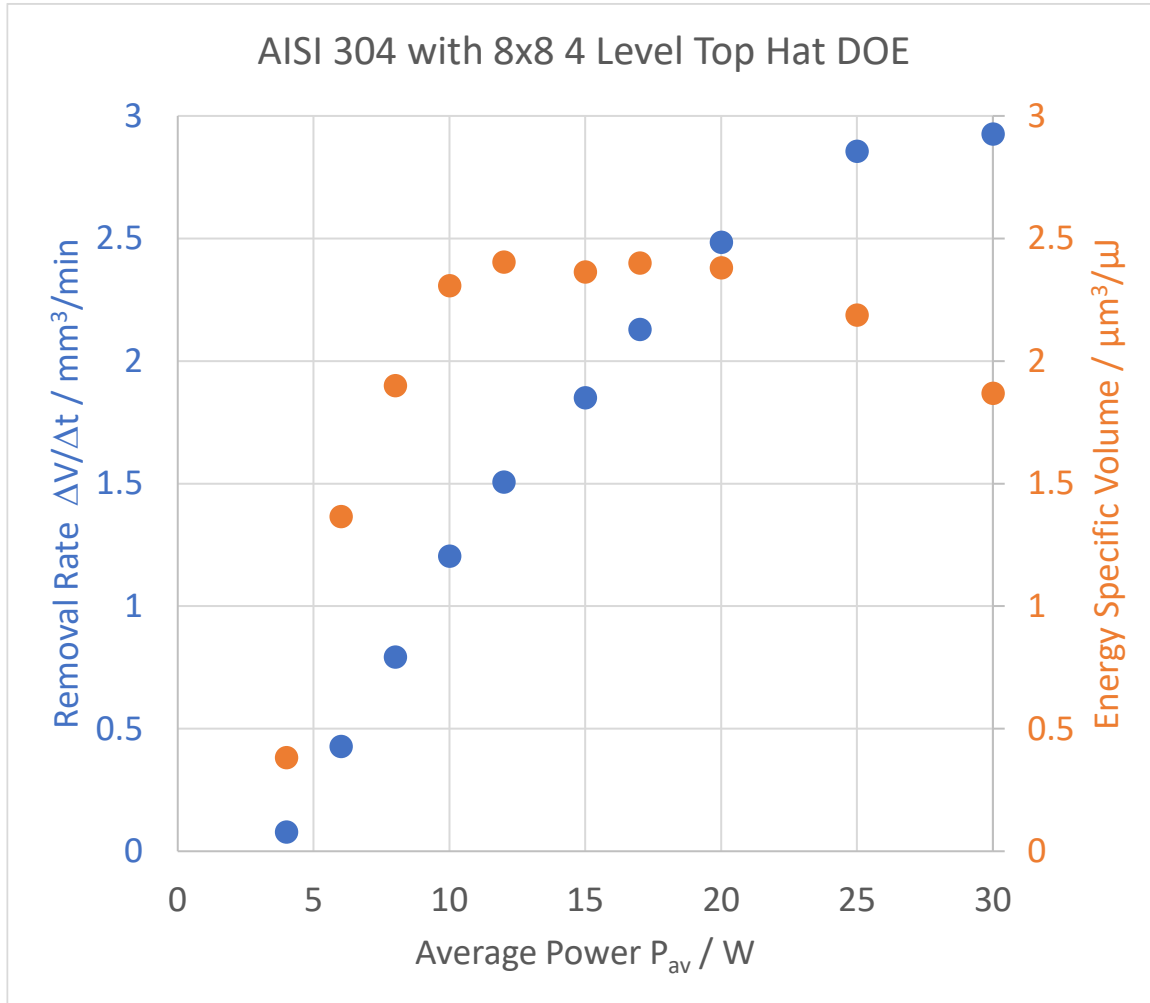


▶ Achieved Pattern



- ▶ Efficiency: 87%
- ▶ 14mm scanner aperture cuts higher diffraction orders
- ▶ Desired pattern not obtained
- ▶ Scanner with bigger aperture needed
- ▶ Experiments performed as planned

Homogeneous Ablation with 8x8 4 Level Top Hat DOE



- ▶ "theoretical" maximum energy specific volume: $2.75 \frac{\mu\text{m}^3}{\mu\text{J}}$ (top hat distribution, 4 Level DOE)

- ▶ Achieved value: $\approx 2.5 \frac{\mu\text{m}^3}{\mu\text{J}}$

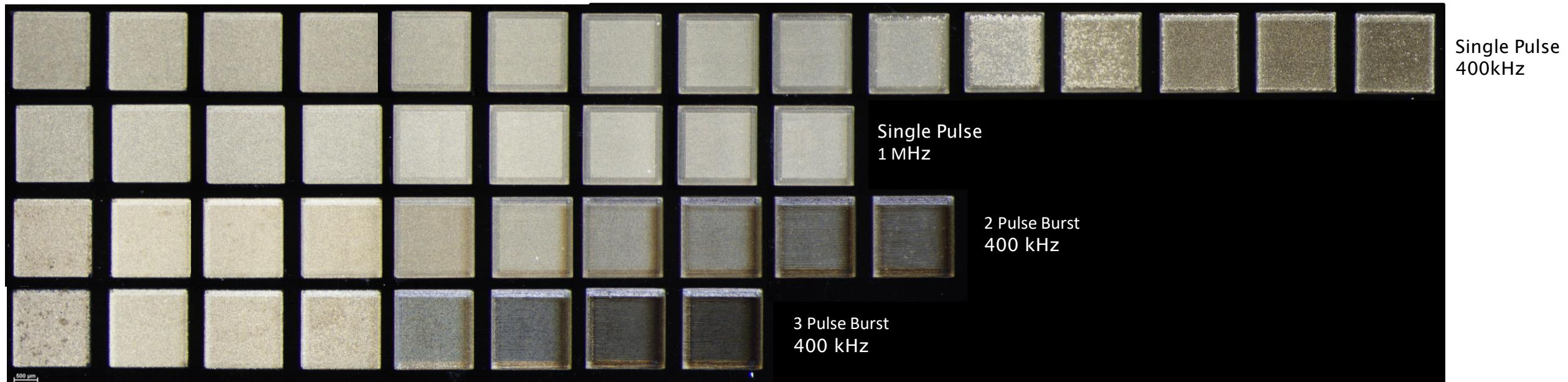
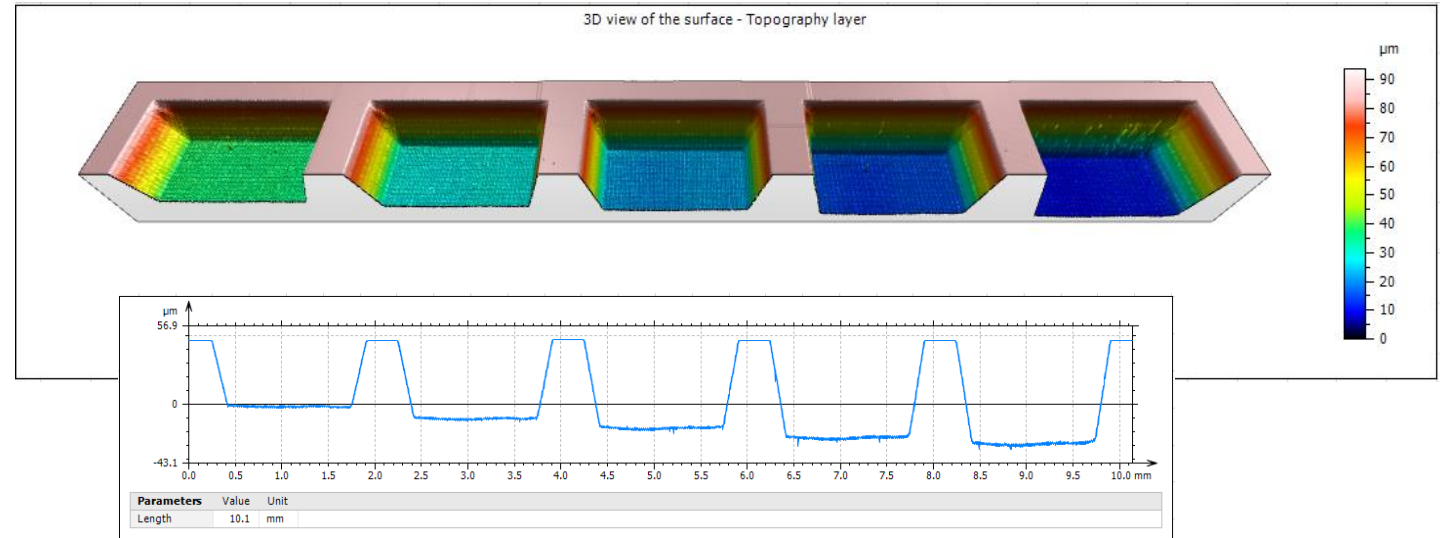
- ▶ $v_{mark,limit} = 20 \frac{\text{m}}{\text{s}}$, $v_{mark,used} = 4 \text{ m/s}$

- ▶ Newest Results with single Pulses (@Lumentum) :

$$P_{av} = 180 \text{ W}, f_r = 1 \text{ MHz}, \frac{\Delta V}{\Delta t} \approx 16 \frac{\text{mm}^3}{\text{min}}$$

4 Level Top Hat DOE: Stainless Steel

- ▶ homogeneous flat bottom with low walls steepness



Conclusion / Outlook

- ▶ The scale-up process of single beams with low pulse energy is limited and would demand extremely high marking speeds
- ▶ Working with high pulse energies
 - ▶ Bursts may help to distribute the energy among several sub-pulses
 - ▶ GHz bursts are like ns pulses, but can be used for hybrid processes
 - ▶ Multi – spot processing (DOE + Scanner) can be applied for periodic structures
 - ▶ Beam forming with DOE allows the efficient use of high pulse energies and reduces the demanded repetition rate
- ▶ The combination of beam forming elements with conventional scanning devices is a promising approach to work with future 1000 W of average power.

Thank you for your kind attention